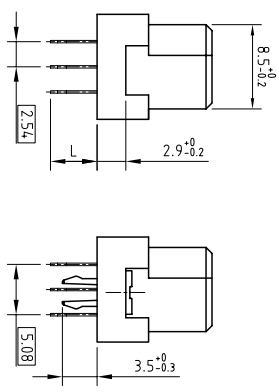


PCB DRILLING DETAILS

- NOTES:
1. THE "LF" PRODUCTS MEET EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
 2. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 3.5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6 MM MINIMUM THICK CIRCUIT BOARD.
 3. LEAD FREE OR ROHS DIRECTIVE LABELING TO BE PROVIDED AS PER GS-14-920 FOR LEAD FREE VERSION.



NO OPTION

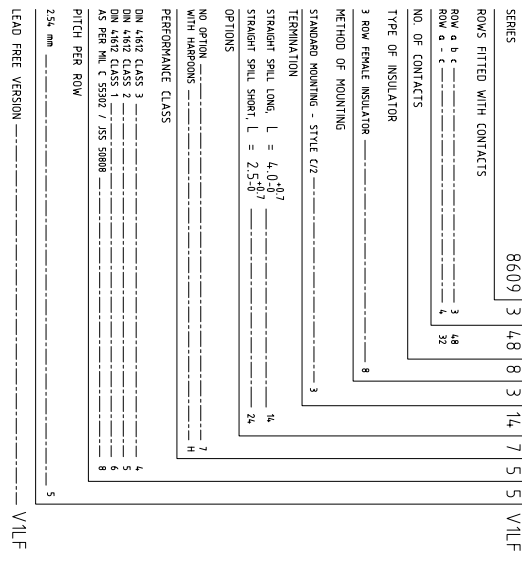
WITH HARPOONS

TECHNICAL SPECIFICATION

HOUSING MATERIAL : THERMOPLASTIC POLYESTER UL94V0, GREY
 HOUSING CAN WITHSTAND EXPOSURE TO LEAD FREE WAVE SOLDERING TEMPERATURE OF 260-265°C
 FOR STRAIGHT CONNECTORS AS IT IS IN CLASSICAL LEAD WAVE SOLDERING AT 235-250°C
 CONTACT & HARPOON MATERIAL : COPPER ALLOY
 CONTACT PLATING :
 ACTIVE ZONE : AU OVER Ni
 TERMINATION ZONE : Sn (PURE HATTI) OVER Ni
 HARPOON PLATING : Sn (PURE HATTI) OVER Ni
 ELECTRICAL DATA
 CURRENT RATING AT 20°C : 15 A
 CURRENT @ MAX : 2 A
 TEMPERATURE RANGE : -55°C TO +105°C
 CONTACT RESISTANCE : ≤ 20 mΩ
 INSULATION RESISTANCE : ≥10¹⁰ MΩ
 TEST VOLTAGE (rms) : 1000 V

MECHANICAL DATA

INSERTION FORCE PER CONTACT : ≤ 0.94 N
 EXTRACTION FORCE PER CONTACT : ≥ 0.15 N
 REFERENCE SPECIFICATION : DIN 41612 / IEC 603-2



LEAD FREE VERSION VILF

mod'l. code	SEE TECH. SPEC.	surface	ISO 1302	tolerance	ISO 1101	projection	product family	8609
Itf	ecn no dr	KR	2008-12-19	tolerances unless otherwise specified		mm	title	DIN STANDARD RECEPTACLE
A	08-071			0±0.1	linear	scale 2:1	STRAIGHT SPILL DIN 41612 STYLE C/2	
		engr	KESAVAN R	0±0.1			dwg no	C-8609-2140
		chr	KESAVAN R				sheet 1 of 1	A3
		opcd	BIJU K PAUL				Product Customer Drawing	
sheet index	revision	sheet	A					

